

DATA SHEET

NEC

GaAs INTEGRATED CIRCUIT μ PG2009TB

L-BAND HIGH POWER SPDT SWITCH

DESCRIPTION

The μ PG2009TB is an L-band SPDT (Single Pole Double Throw) GaAs FET switch which was developed for digital cellular or cordless telephone application. The device can operate from 500 MHz to 2.5 GHz, having the low insertion loss and high isolation by 2.8 V control voltage.

FEATURES

- Low insertion loss : $L_{INS} = 0.25$ dB TYP. @ $V_{cont1/2} = 2.8$ V/0 V, $f = 1.0$ GHz
 $L_{INS} = 0.30$ dB TYP. @ $V_{cont1/2} = 2.8$ V/0 V, $f = 2.0$ GHz
- High isolation : $ISL = 28$ dB TYP. @ $V_{cont1/2} = 2.8$ V/0 V, $f = 2.0$ GHz
- High power : $P_{in(0.1dB)} = 34$ dBm TYP. @ $V_{cont1/2} = 2.8$ V/0 V, $f = 1.0$ GHz
- 6-pin super minimold package ($2.0 \times 1.25 \times 0.9$ mm)

APPLICATION

- L-band digital cellular or cordless telephone
- Bluetooth™, W-LAN and WLL applications

ORDERING INFORMATION

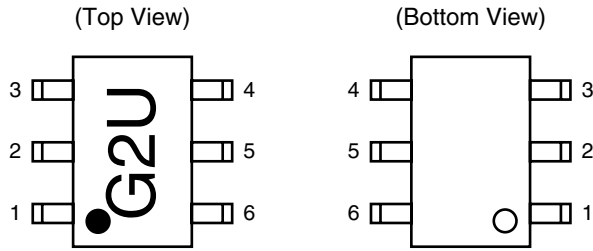
| Part Number | Package | Marking | Supplying Form |
|-------------------|----------------------|---------|---|
| μ PG2009TB-E3 | 6-pin super minimold | G2U | <ul style="list-style-type: none">• Embossed tape 8 mm wide• Pin 1, 2, 3 face the perforation side of the tape• Qty 3 kpcs/reel |

Remark To order evaluation samples, contact your nearby sales office.
Part number for sample order: μ PG2009TB

Caution Observe precautions when handling because these devices are sensitive to electrostatic discharge.

The information in this document is subject to change without notice. Before using this document, please confirm that this is the latest version.
Not all devices/types available in every country. Please check with local NEC Compound Semiconductor Devices representative for availability and additional information.

★ PIN CONNECTIONS



| Pin No. | Pin Name |
|---------|--------------------|
| 1 | OUT1 |
| 2 | GND |
| 3 | OUT2 |
| 4 | V _{cont2} |
| 5 | IN |
| 6 | V _{cont1} |

ABSOLUTE MAXIMUM RATINGS (T_A = +25°C, unless otherwise specified)

| Parameter | Symbol | Ratings | Unit |
|-------------------------------|-----------------------|------------------------------|------|
| Control Voltage 1, 2 | V _{cont1, 2} | -6.0 to +6.0 ^{Note} | V |
| Input Power | P _{in} | +36 | dBm |
| Total Power Dissipation | P _{tot} | 0.15 | W |
| Operating Ambient Temperature | T _A | -45 to +85 | °C |
| Storage Temperature | T _{stg} | -55 to +150 | °C |

Note |V_{cont1}-V_{cont2}| ≤ 6.0 V

RECOMMENDED OPERATING RANGE (T_A = +25°C)

| Parameter | Symbol | MIN. | TYP. | MAX. | Unit |
|------------------------|----------------------|------|------|------|------|
| Control Voltage (High) | V _{cont(H)} | +2.7 | +2.8 | +3.0 | V |
| Control Voltage (Low) | V _{cont(L)} | -0.2 | 0 | +0.2 | V |

ELECTRICAL CHARACTERISTICS

($T_A = +25^\circ\text{C}$, $V_{\text{cont}1} = 2.8\text{ V}$, $V_{\text{cont}2} = 0\text{ V}$ or $V_{\text{cont}1} = 0\text{ V}$, $V_{\text{cont}2} = 2.8\text{ V}$, $Z_o = 50\ \Omega$, Off chip DC blocking capacitors value; 56 pF, unless otherwise specified)

| Parameter | Symbol | Test Conditions | MIN. | TYP. | MAX. | Unit |
|---|-------------------------|---|------|------|------|------|
| Insertion Loss | L _{INS} | f = 0.5 to 1.0 GHz | – | 0.25 | 0.45 | dB |
| | | f = 2.0 GHz | – | 0.30 | 0.50 | dB |
| | | f = 2.5 GHz | – | 0.40 | – | dB |
| Isolation | ISL | f = 0.5 to 2.0 GHz | 24 | 28 | – | dB |
| | | f = 2.5 GHz | – | 25 | – | dB |
| Input Return Loss | RL _{in} | f = 0.5 to 2.5 GHz | 15 | 20 | – | dB |
| Output Return Loss | RL _{out} | f = 0.5 to 2.5 GHz | 15 | 20 | – | dB |
| Input Power at 0.1 dB Compression Point ^{Note} | P _{in(0.1 dB)} | f = 1.0 GHz, V _{cont} = 2.8 V/0 V | 32.5 | 34 | – | dBm |
| 2nd Harmonics | 2f ₀ | f = 1.0 GHz, V _{cont} = 2.8 V/0 V, P _{in} = 30.5 dBm | 65 | 75 | – | dBc |
| 3rd Harmonics | 3f ₀ | f = 1.0 GHz, V _{cont} = 2.8 V/0 V, P _{in} = 30.5 dBm | 65 | 75 | – | dBc |
| Switching Speed | t _{sw} | | – | 150 | – | ns |
| Control Current | I _{cont} | V _{cont} = 2.8 V/0 V, RF Non | – | 1 | 50 | μA |

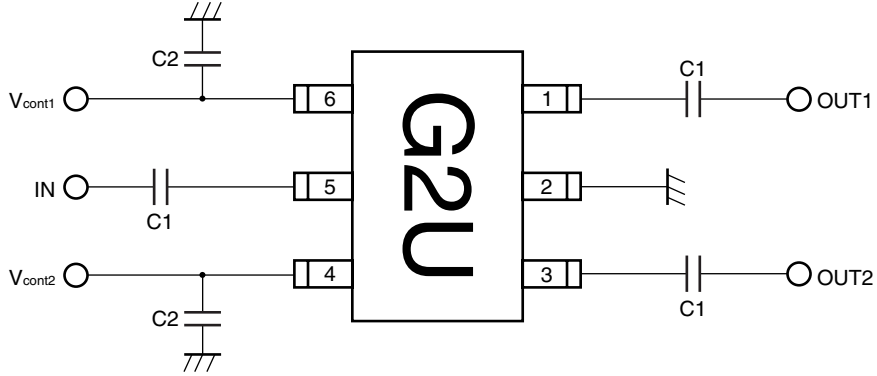
Note P_{in(0.1 dB)} are measured the input power level when the insertion loss increase more 0.1 than that of linear range. All other characteristics are measured in linear range.

Caution When the μPG2009TB is used it is necessary to use DC blocking capacitors for No.1 (OUT1), No.3 (OUT2) and No.5 (IN). The value of DC blocking capacitors should be chosen to accommodate the frequency of operation, bandwidth, switching speed and the condition with actual board of your system.

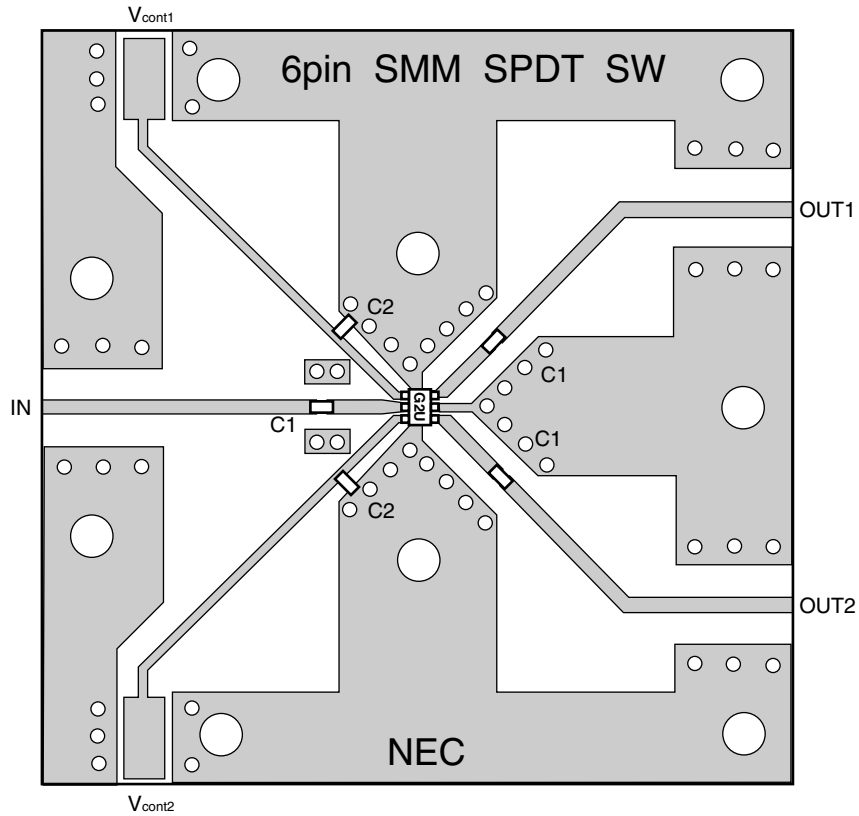
The range of recommended DC blocking capacitor value is less than 100 pF.

EVALUATION CIRCUIT

$V_{cont1} = 2.8\text{ V}$, $V_{cont2} = 0\text{ V}$ or $V_{cont2} = 0\text{ V}$, $V_{cont1} = 2.8\text{ V}$, off chip DC blocking capacitors value $C1 = 56\text{ pF}$, $C2 = 1\text{ 000 pF}$ (Bypass), using NEC standard evaluation board.



EVALUATION BOARD

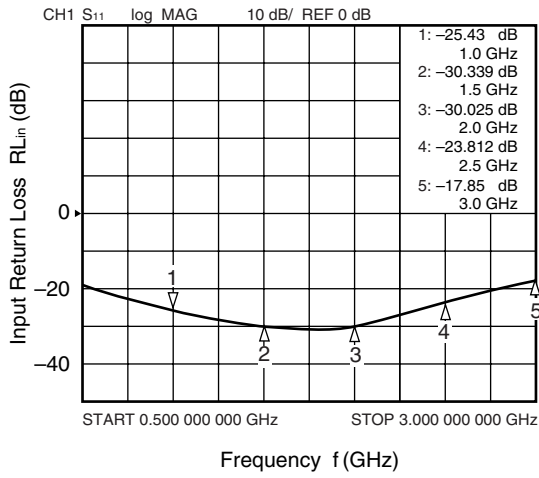


TRUTH TABLE

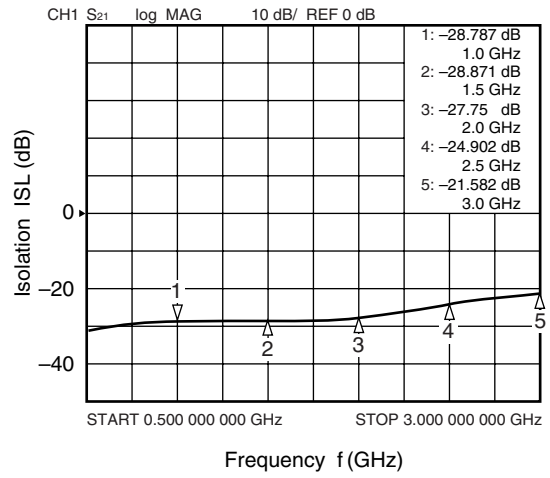
| V_{cont1} | V_{cont2} | IN-OUT1 | IN-OUT2 |
|-------------|-------------|---------|---------|
| Low | High | OFF | ON |
| High | Low | ON | OFF |

TYPICAL CHARACTERISTICS ($T_A = +25^{\circ}\text{C}$, $V_{\text{cont}1/2} = 2.8 \text{ V/0 V}$, $P_{\text{in}} = 0 \text{ dBm}$, **OUT2 side is 50 Ω termination, unless otherwise specified**)

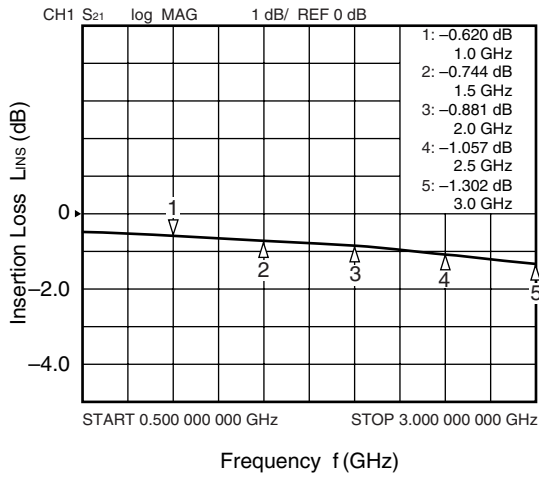
INPUT RETURN LOSS vs. FREQUENCY



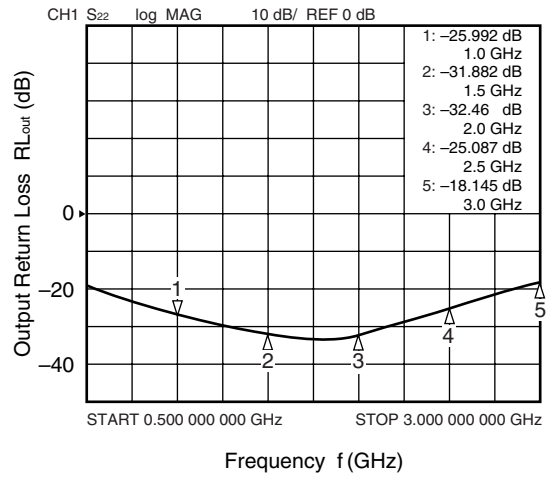
ISOLATION vs. FREQUENCY



INSERTION LOSS vs. FREQUENCY



OUTPUT RETURN LOSS vs. FREQUENCY



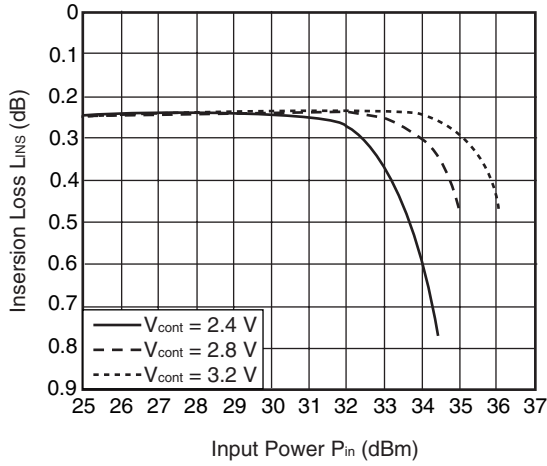
Caution These characteristics values include the losses of the NEC evaluation board.

Remark The graphs indicate nominal characteristics.

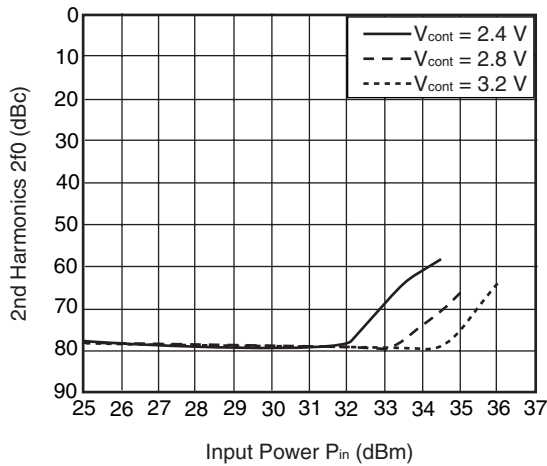
TYPICAL CHARACTERISTICS

(f = 2 GHz, OUT2 side is 50 Ω termination, unless otherwise specified)

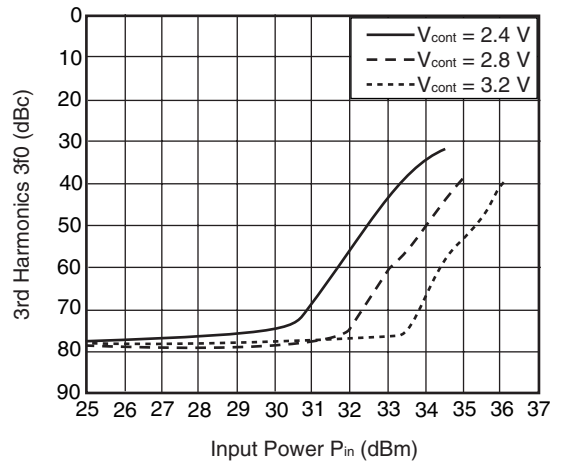
RELATION BETWEEN CONTROL VOLTAGE OF INSERTION LOSS



RELATION BETWEEN CONTROL VOLTAGE OF 2nd HARMONICS



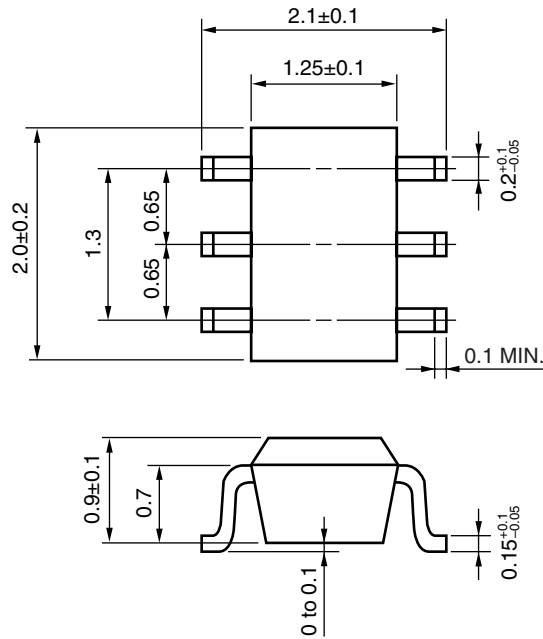
RELATION BETWEEN CONTROL VOLTAGE OF 3rd HARMONICS



Remark The graphs indicate nominal characteristics.

PACKAGE DIMENSIONS

6-PIN SUPER MINIMOLD (UNIT: mm)



RECOMMENDED SOLDERING CONDITIONS

This product should be soldered and mounted under the following recommended conditions. For soldering methods and conditions other than those recommended below, contact your nearby sales office.

| Soldering Method | Soldering Conditions | Condition Symbol |
|------------------|---|------------------|
| Infrared Reflow | Peak temperature (package surface temperature) : 260°C or below Time at peak temperature : 10 seconds or less Time at temperature of 220°C or higher : 60 seconds or less Preheating time at 120 to 180°C : 120±30 seconds Maximum number of reflow processes : 3 times Maximum chlorine content of rosin flux (% mass) : 0.2%(Wt.) or below | IR260 |
| VPS | Peak temperature (package surface temperature) : 215°C or below Time at temperature of 200°C or higher : 25 to 40 seconds Preheating time at 120 to 150°C : 30 to 60 seconds Maximum number of reflow processes : 3 times Maximum chlorine content of rosin flux (% mass) : 0.2%(Wt.) or below | VP215 |
| Wave Soldering | Peak temperature (molten solder temperature) : 260°C or below Time at peak temperature : 10 seconds or less Preheating temperature (package surface temperature) : 120°C or below Maximum number of flow processes : 1 time Maximum chlorine content of rosin flux (% mass) : 0.2%(Wt.) or below | WS260 |
| Partial Heating | Peak temperature (pin temperature) : 350°C or below Soldering time (per side of device) : 3 seconds or less Maximum chlorine content of rosin flux (% mass) : 0.2%(Wt.) or below | HS350 |

Caution Do not use different soldering methods together (except for partial heating).

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M8E 00.4-0110

SAFETY INFORMATION ON THIS PRODUCT

| | | |
|-----------------------|----------------------|---|
| <p>Caution</p> | <p>GaAs Products</p> | <p>The product contains gallium arsenide, GaAs. GaAs vapor and powder are hazardous to human health if inhaled or ingested.</p> <ul style="list-style-type: none"> • Do not destroy or burn the product. • Do not cut or cleave off any part of the product. • Do not crush or chemically dissolve the product. • Do not put the product in the mouth. <p>Follow related laws and ordinances for disposal. The product should be excluded from general industrial waste or household garbage.</p> |
|-----------------------|----------------------|---|

► For further information, please contact

NEC Compound Semiconductor Devices, Ltd. <http://www.ncsd.necel.com/>

E-mail: salesinfo@ml.ncsd.necel.com (sales and general)

techinfo@ml.ncsd.necel.com (technical)

Sales Division TEL: +81-44-435-1588 FAX: +81-44-435-1579

NEC Compound Semiconductor Devices Hong Kong Limited

E-mail: ncsd-hk@elhk.nec.com.hk (sales, technical and general)

Hong Kong Head Office TEL: +852-3107-7303 FAX: +852-3107-7309

Taipei Branch Office TEL: +886-2-8712-0478 FAX: +886-2-2545-3859

Korea Branch Office TEL: +82-2-558-2120 FAX: +82-2-558-5209

NEC Electronics (Europe) GmbH <http://www.ee.nec.de/>

TEL: +49-211-6503-0 FAX: +49-211-6503-1327

California Eastern Laboratories, Inc. <http://www.cel.com/>

TEL: +1-408-988-3500 FAX: +1-408-988-0279